



# SOT1591-3

HVQFN16, plastic, thermal enhanced very thin quad flatpack; no leads; 16 terminals; 0.5 mm pitch; 3 mm x 3 mm x 0.85 mm body

7 August 2018

Package information

## 1 Package summary

|                                       |  |
|---------------------------------------|--|
| <b>Terminal position code</b>         | Q (quad)   |
| <b>Package type descriptive code</b>  | HVQFN16  |
| <b>Package type industry code</b>     | HVQFN16  |
| <b>Package style descriptive code</b> | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| <b>Package body material type</b>     | P (plastic)  |
| <b>Mounting method type</b>           | S (surface mount)  |
| <b>Issue date</b>                     | 01-08-2018   |
| <b>Manufacturer package code</b>      | 98ASA00741D  |

Table 1. Package summary

| Parameter                      | Min | Nom  | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length                 | -   | 3    | -   | mm   |
| package width                  | -   | 3    | -   | mm   |
| package height                 | -   | 0.85 | -   | mm   |
| nominal pitch                  | -   | 0.5  | -   | mm   |
| actual quantity of termination | -   | 16   | -   |      |



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2 Package outline

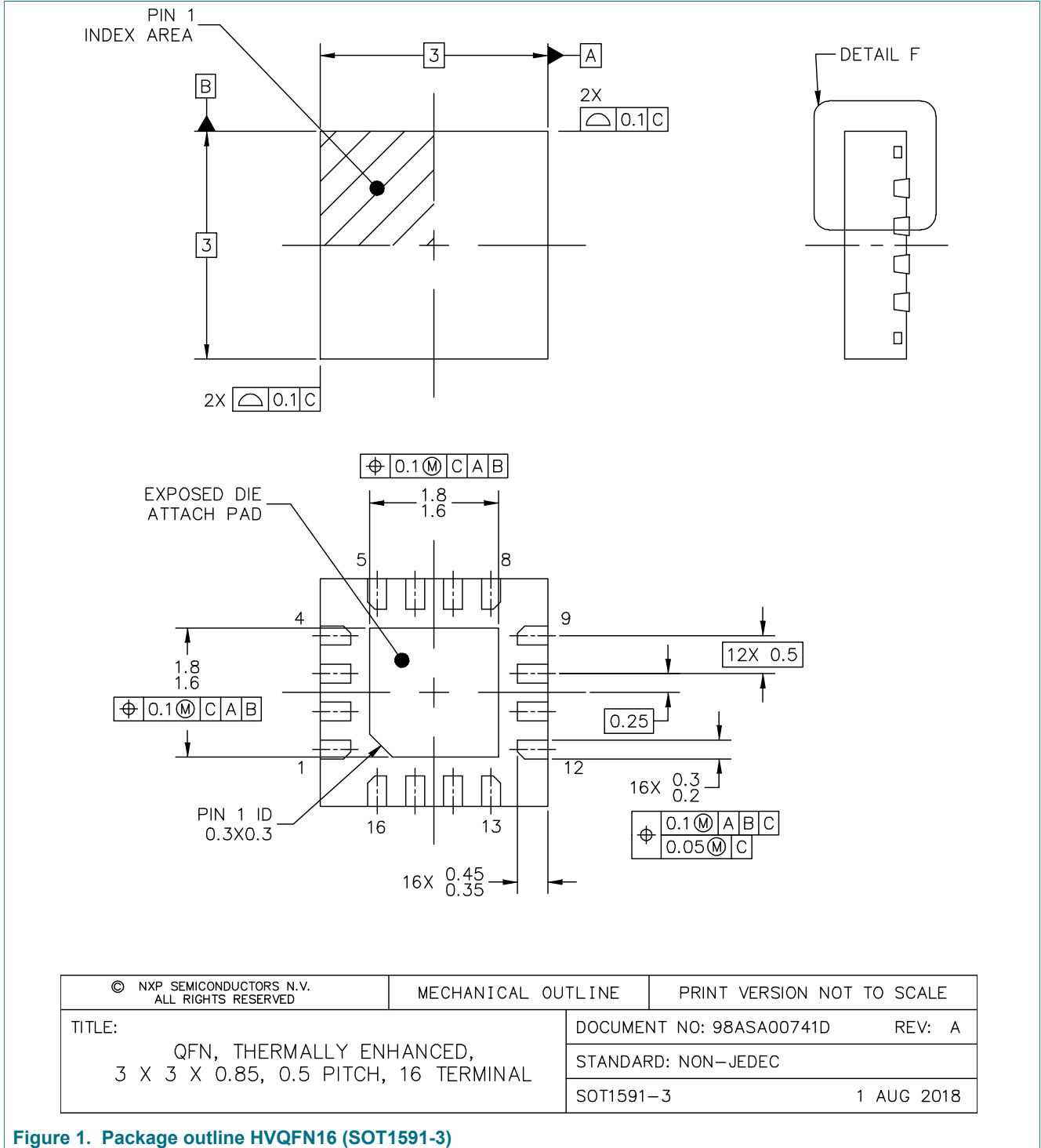


Figure 1. Package outline HVQFN16 (SOT1591-3)

HVQFN16, plastic, thermal enhanced very thin quad flatpack; no leads; 16 terminals; 0.5 mm pitch; 3 mm x 3 mm x 0.85 mm body

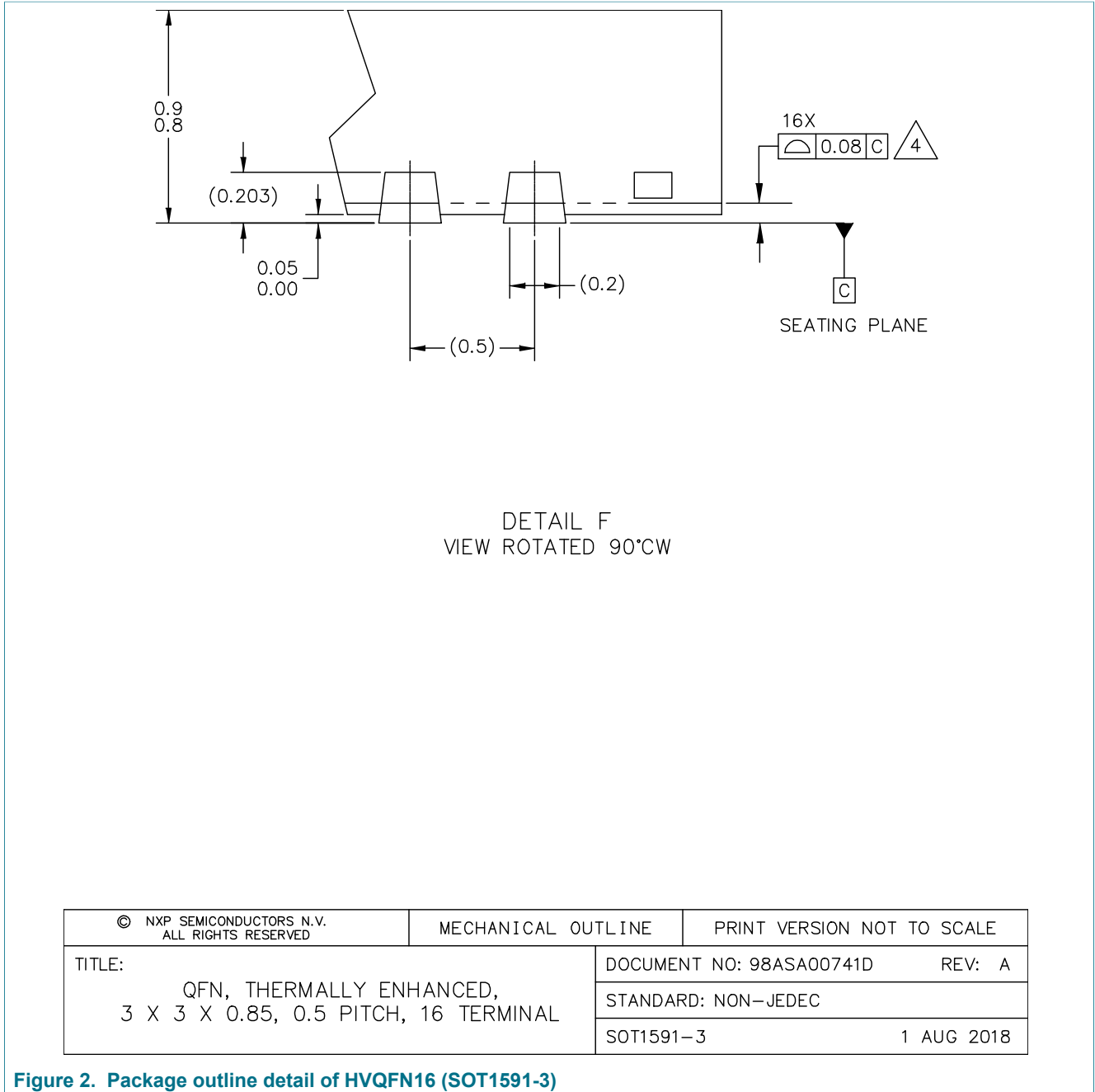



Figure 2. Package outline detail of HVQFN16 (SOT1591-3)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

|  |                          |                            |
|--|--------------------------|----------------------------|
| © NXP SEMICONDUCTORS N.V.<br>ALL RIGHTS RESERVED                           | MECHANICAL OUTLINE       | PRINT VERSION NOT TO SCALE |
| TITLE:<br>QFN, THERMALLY ENHANCED,<br>3 X 3 X 0.85, 0.5 PITCH, 16 TERMINAL | DOCUMENT NO: 98ASA00741D | REV: A                     |
|  | STANDARD: NON-JEDEC      |                            |
|  | SOT1591-3                | 1 AUG 2018                 |

Figure 3. Package outline note HVQFN16 (SOT1591-3)

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### 3 Legal information

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